APPLICA	BLE STAN	IDARD								
OPERATING TEMPERATU		RE BANGE	-35°C TO +85 °C(NOTE 1)		STORAGE EMPERATU	RE BANGE	-	-10°C TO +60°C(NO		3)
RATING	OPERATING HUMIDITY RANGE		20 % TO 80 % (NOTE	2) S	STORAGE HUMIDITY F			40 % TO 70 %(NOTE		
	VOLTAGE		AC 150 V		APPLICABLE CONNECTOR		DF13-*S-1.2		iC	
	CURRENT		1 A		APPLICABLE CONTACT			DF13(G)-26309 DF13-3032S0		
	1		SPECIFI	CATI	ONS		•			
ΙT	EM		TEST METHOD			RE	QUIRI	EMENTS	QT	АТ
	RUCTION									
GENERAL EXAMINATION MARKING			VISUALLY AND BY MEASURING INSTRUMENT. CONFIRMED VISUALLY.			ACCORDING TO DRAWING.				X
ELECTR	IC CHARA	CTERI	STICS							
	RESISTANCE				30 ms	30 mΩ MAX.				_
INSULATION RESISTANCE		100 V DC.			500 M	500 MΩ MIN.				_
VOLTAGE PROOF		500 V AC FOR 1 min.			NO FL	NO FLASHOVER OR BREAKDOWN.				_
MECHAN	IICAL CHA	ARACTI	ERISTICS		I					
MECHANICA OPERATION		30 TIME				 CONTACT RESISTANCE: 30 mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				_
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			① NO	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF				
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			PAF	PARTS.				_
ENVIRO	NMENTAL	CHAR	ACTERISTICS		•					.1
RAPID CHA						① CONTACT RESISTANCE: 30mΩ MAX.				
TEMPERATURE			UNDER 5 CYCLES.			(2) INSULATION RESISTANCE: $500~\text{M}\Omega$ MIN. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				_
DAMP HEAT (STEADY STATE)		EXPOSE	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.							_
RESISTANC	E TO	1) REFLO	1) REFLOW SOLDERING			NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.				
SOLDERING	G HEAT		≪REFLOW AREA≫ MAX250°C WITHIN 10 sec							_
		MIN 230°C WITHIN 60 sec				TETUVIIVALO.				
			HEATING AREA							
		170°C to 190°C 60 sec to 120 sec PUT THROUGH IN REFLOW FURNACE TWICE LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW.								
		, -	AL SOLDERING RING IRON TEMPERATURE :350℃,							
			RING TIME: 3sec.							
OOL DEDADULTY		NO STRENGTH ON CONTACT.				COLDED CHALL COVED A MINIMUM OF				
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE, 245±3°C FOR INSERTION DURATION, 3sec.				SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				_
REMARKS		1= :-=-	, , , , , , , , , , , , , , , , , , , ,		1 44 / 4					
NOTE1: INCLI NOTE2: NO C	_	PERATURE	RISING BY CURRENT							
		IDITION OF	LONG TERM STORAGE FOR UNUS	ED PROD	UCTS BEFO	RE MOUNT	ED ON	I PCB.		
	R MOUNTED (ON PCB B	OARD, OPERATING TEMPERATUR	RE AND H	HUMIDITY R	ANGE IS A	PPLIE	O FOR INTERIM STOR	AGE DU	JRING
		ESCRIPTI	SCRIPTION OF REVISIONS DESIG			NED CHECKED				\TE
Δ									1	
Unless other	erwise speci	fied, refer	ed, refer to IEC 60512.			APPROVE	ED	HS.OKAWA)4.05
						CHECKE	D	TS.FUKUSHIMA	18.0)4.05
						DESIGNE	D	TS.KUMAZAWA	18.0)4.05
			T			DRAWN)4.05
						RAWING NO.		ELC-083664-75-00		
HS		SPECIFICATION SHEET			RT NO.	DF13-*P-1.25V(75)			A	4 1 1
	HIP	HIROSE ELECTRIC CO., LTD.			DE NO.	CL536		L536	∇	1/1